MOSFET – Dual, N-Channel, Small Signal

20 V, 540 mA

Features

- Low R_{DS(on)} Improving System Efficiency
- Low Threshold Voltage
- Small Footprint 1.6 x 1.6 mm
- ESD Protected Gate
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Cell Phones, Digital Cameras, PDAs, Pagers, etc.

MAXIMUM RATINGS (T_{.I} = 25°C unless otherwise noted.)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	20	V
Gate-to-Source Voltage			V_{GS}	±7.0	V
Continuous Drain Current	Steady T _A = 25°C		I_	540	mA
(Note 1)	State	$T_A = 85^{\circ}C$	I _D	390	
Power Dissipation (Note 1)	Steady State		P _D	250	mW
Continuous Drain Current	t ≤ 5 s	$T_A = 25^{\circ}C$	I _D	570	mA
(Note 1)	1 ≥ 5 5	$T_A = 85^{\circ}C$	טי	410	
Power Dissipation (Note 1)	t ≤ 5 s		P _D	280	mW
Pulsed Drain Current	t _p =	: 10 μs	I _{DM}	1.5	Α
Operating Junction and Storage Temperature			T _J , T _{STG}	-55 to 150	°C
Source Current (Body Diode)			IS	350	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{ heta JA}$	500	°C/W
Junction-to-Ambient – $t \le 5$ s (Note 1)		447	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

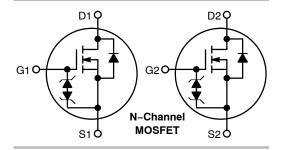
1. Surface mounted on FR4 board using 1 in sq pad size (Cu. area = 1.127 in sq [1 oz] including traces).



ON Semiconductor®

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V _{(BR)DSS} R _{DS(on)} Typ		I _D Max (Note 1)	
20	400 mΩ @ 4.5 V		
	500 mΩ @ 2.5 V	540 mA	
	700 mΩ @ 1.8 V		



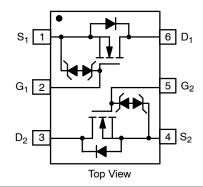


TV = Specific Device Code M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

PINOUT: SOT-563



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted.)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		20	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	-		-	14	-	mV/°C
Zero Gate Voltage Drain Current		V _{GS} = 0 V	T _J = 25°C	-	-	1.0	μΑ
	I _{DSS}	V _{DS} = 16 V	T _J = 125°C	-	-	5.0	
Gate-to-Source Leakage Current	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 4	1.5 V	_	-	±5.0	μΑ
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250$	μΑ	0.45	-	1.0	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	-		-	2.0	-	mV/°C
Drain-to-Source On Resistance		$V_{GS} = 4.5 \text{ V}, I_D = 540$) mA	-	0.4	0.55	Ω
	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 500) mA	-	0.5	0.7	
		V _{GS} = 1.8 V, I _D = 350 mA		-	0.7	0.9	
Forward Transconductance	9FS	V _{DS} = 10 V, I _D = 540 mA		-	1.0	-	S
CHARGES AND CAPACITANCES	•						
Input Capacitance	C _{ISS}			-	80	150	pF
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1.0 MHz, V	_{DS} = 16 V	-	13	25	
Reverse Transfer Capacitance	C _{RSS}			-	10	20	
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 4.5 V, V_{DS} = 10 V; I_{D} = 540 mA		-	1.5	2.5	nC
Threshold Gate Charge	Q _{G(TH)}			-	0.1	-	
Gate-to-Source Charge	Q _{GS}			-	0.2	-	
Gate-to-Drain Charge	Q_{GD}			-	0.35	-	
SWITCHING CHARACTERISTICS, V _{GS} = V	Note 4)				-		
Turn-On Delay Time	t _{d(ON)}			-	6.0	-	ns
Rise Time	t _r	V_{GS} = 4.5 V, V_{DD} = 10 V, I_{D} = 540 mA, R_{G} = 10 Ω		-	4.0	-	
Turn-Off Delay Time	t _{d(OFF)}			_	16	_	
Fall Time	t _f			-	8.0	-	
DRAIN-SOURCE DIODE CHARACTERISTIC	s			<u> </u>	<u> </u>	-	-
Forward Diode Voltage	.,	V _{GS} = 0 V,	T _J = 25°C	-	0.7	1.2	V
	V _{SD}	$I_{S} = 350 \text{ mA}$ $T_{J} = 125^{\circ}\text{C}$		-	0.6	-	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V}, d_{ISD}/d_t = 100 \text{ A/}\mu\text{s}, I_S = 350 \text{ mA}$		-	6.5	_	ns
	•	1 1 1 1 1 1					

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Surface—mounted on FR4 board using 1 in. sq. pad size (Cu. area = 1.127 in sq [1 oz] including traces).

- Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

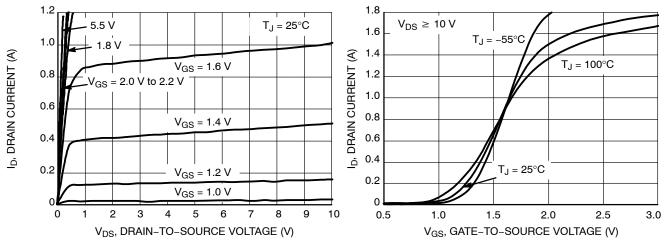


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

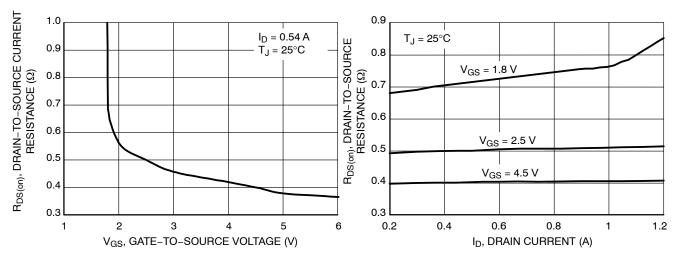


Figure 3. On-Resistance versus Gate-to-Source Voltage

Figure 4. On-Resistance versus Drain Current and Gate Voltage

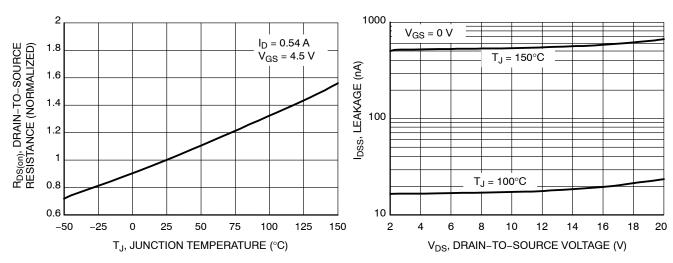
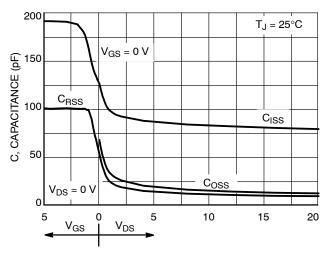


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current versus Voltage

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)



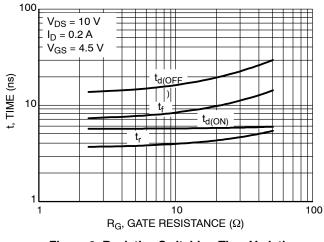
 $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ $^{\circ}$ OPAIN–TO–SOURCE VOLTAGE (V) V_{GS}, GATE-TO-SOURCE VOLTAGE (V) V_{DS} V_{GS} Q_{GS} Q_{GD} $I_D = 0.54 A$ $T_J = 25^{\circ}C$ 0 0.2 0 0.4 0.6 0.8 1.2 1.4 1.6 Qg, TOTAL GATE CHARGE (nC)

 Q_T

GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (V)

Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge





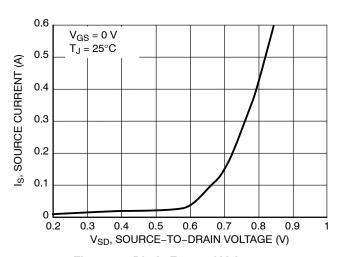


Figure 9. Resistive Switching Time Variation versus Gate Resistance

Figure 10. Diode Forward Voltage versus Current

ORDERING INFORMATION

Device	Package	Shipping
NTZD3154NT1G		
NTZD3154NT1H	SOT-563 (Pb-Free)	4000 / Tana 9 Basi
NTZD3154NT2G		4000 / Tape & Reel
NTZD3154NT2H		
NTZD3154NT5G		2000 / Tong 9 Dool
NTZD3154NT5H		8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



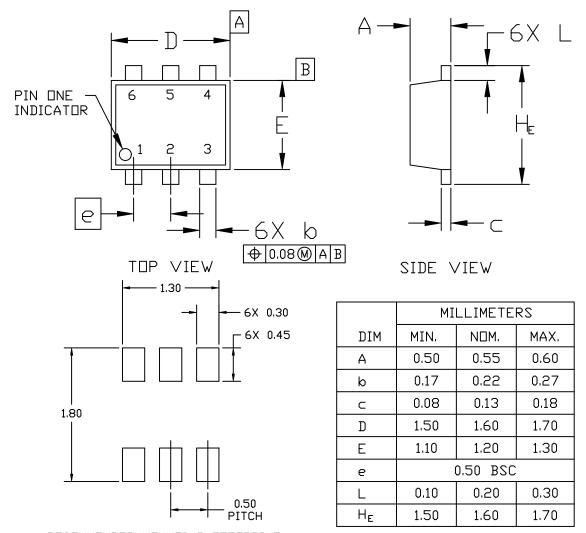


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NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



RECOMMENDED MOUNTING FOOTPRINT*

For additional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

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STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 2: PIN 1. EMITTER 1 2. EMITTER 2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE 1
	STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE	
	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	
STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

M = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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